



PRESS RELEASE

## Universal Partners with NextFlex to Showcase Heterogeneous Integration Solution at SEMICON West

Pioneering solution enables efficient volume manufacturing for complex multi-die devices.

Universal Instruments will exhibit on Booth 1031 at the SEMICON West trade show in San Francisco, CA on December 7–9. On the booth, Universal will feature its FuzionSC™ Platform equipped with a High-Speed Wafer Feeder (HSWF) – both generously on loan from NextFlex, America’s Flexible Hybrid Electronics Manufacturing Institute.

The FuzionSC Platform delivers precision accuracy, the widest component range and the highest flip chip throughput across the largest area. With the ability to handle all facets of flip chip assembly, FuzionSC reduces operating and capital costs by maximizing throughput per floor space. The HSWF is the world’s fastest rapid-exchange multi-die feeder. Combined with FuzionSC, it is the ultimate multi-die solution for heterogeneous integration.

“Advanced Semiconductor Packaging concepts are coalescing around heterogeneous integration solutions,” noted Universal Instruments Vice President of Marketing, Glenn Farris. “Die-to-die integration via silicon interposers, chiplets, fan-out technology or a combination of these are proliferating. In order to achieve high yields for these new applications, an in situ solution is required and that was our objective from the start. We therefore focused our efforts on attaining the flexibility, accuracy and throughput necessary to place multiple die types in a single cell and enable the world’s only all-in-one solution for heterogeneous integration.”

NextFlex is a consortium of American electronics companies, academic institutions, non-profits and state, local and federal government partners with the shared goal of advancing U.S. manufacturing of printed flexible electronics. NextFlex played an important role in the development of the HSWF, collaborating with Universal along the way and sharing its vision to help align product features and capabilities with current market challenges.

“We are thrilled to have the FuzionSC and High-Speed Wafer Feeder in our advanced lab,” said NextFlex Executive Director, Malcom Thompson. “We are always pushing the technology boundaries and this solution enables us to add incredible capability for thin, multi-wafer and die applications not only for heterogeneous integration, but many other FHE applications.”

Visit us on the booth to see various technologies used in the manufacturing of Flexible Hybrid Electronics (FHE) products. We also encourage you to stop by the Smart MedTech Pavilion on Wednesday, December 8, to speak with NextFlex Director of Technology, Scott Miller, about the different ways that NextFlex is advancing FHE.

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To learn more about Universal’s solutions for any electronics manufacturing challenge, contact Universal Instruments at +1-800-432-2607 or +1-607-779-7522 or visit [www.uic.com](http://www.uic.com).

**About Universal Instruments**

Universal Instruments is a global leader in the design and manufacture of advanced automation and assembly equipment solutions for the electronics manufacturing industry. Universal Instruments delivers comprehensive solutions to a global customer base by leveraging exclusive process expertise combined with its innovative portfolio of flexible platforms for surface mount, insertion mount, advanced semiconductor packaging, and end-of-line automation. Universal Instruments is headquartered in Conklin, N.Y., USA, with offices in Europe, Asia and the Americas.

**About NextFlex**

NextFlex is a DoD sponsored Manufacturing Innovation Institute funded by Air Force Research Laboratory Cooperative Agreement numbers FA8650-15-2-5402 and FA8650-20-2-5506. NextFlex is a consortium of companies, academic institutions, non-profits and state, local and federal governments with a shared goal of advancing U.S. manufacturing of FHE. Since its formation in 2015, NextFlex’s elite team of thought leaders, educators, problem solvers and manufacturers have come together to collectively facilitate innovation, narrow the manufacturing workforce gap and promote sustainable manufacturing ecosystems. For more information, visit [www.nextflex.us](http://www.nextflex.us) and follow NextFlex on [LinkedIn](#), [Facebook](#) and [Twitter](#).

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